

Thermal modeling of hybrid three-dimensional integrated, ring-based silicon photonic–electronic transceivers (Erratum)

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This article [*J. Opt. Microsystems* 4(1), 011004 (2023) doi [10.1117/1.JOM.4.1.011004](https://doi.org/10.1117/1.JOM.4.1.011004)] was originally published on 6 December 2023, with erroneous values in Table 2, as shown below. The UCUT values of Simulation (pm/mW) and Difference (%) were incorrect.

Table 2 Ring modulator heater efficiency from experiments (pm/mW) and simulations (equivalent model) (K/mW). The value between brackets is obtained by the geometric model.

	No UCUT		UCUT	
	No EIC	With EIC	No EIC	With EIC
Experiment (pm/mW)	165	131	312	180
Simulation (K/mW)	3.07	2.14	5.44	2.86 (3.08)
Simulation (pm/mW)	192	134	182	340
Difference (%)	16.3	2.10	1.04	13.3

The table was corrected on 11 March 2024. The corrected table is shown below.

Table 2 Ring modulator heater efficiency from experiments (pm/mW) and simulations (equivalent model) (K/mW). The value between brackets is obtained by the geometric model.

	No UCUT		UCUT	
	No EIC	With EIC	No EIC	With EIC
Experiment (pm/mW)	165	131	312	180
Simulation (K/mW)	3.07	2.14	5.44	2.86 (3.08)
Simulation (pm/mW)	192	134	340	179
Difference (%)	16.3	2.10	8.97	0.55